Power Electronics Materials

NC-SMQ75 Solder Paste

Industry-proven no-clean "Power-Safe" die-attach paste for high-Pb alloys

- Ultra-low post-reflow residue bonds strongly to overmolding materials
- Finished devices proven to AEC-Q101
- Eliminates cost of cleaning

BiAgX® High-Temperature Pb-Free Solder Paste

- >260°C melting alternative to high-Pb solder
- High-reliability up to 200°C Tjmax
- Drops into current high-Pb paste assembly process

HSMF Non-Silicone-Based Thermal Compounds

- Perform well in applications with large area thermal interface requirements
- Inherent adhesive property for easy placement and clean-up
- No pump-out or bake-out over time

Solder Preforms and Ribbons

Wide portfolio to meet all needs

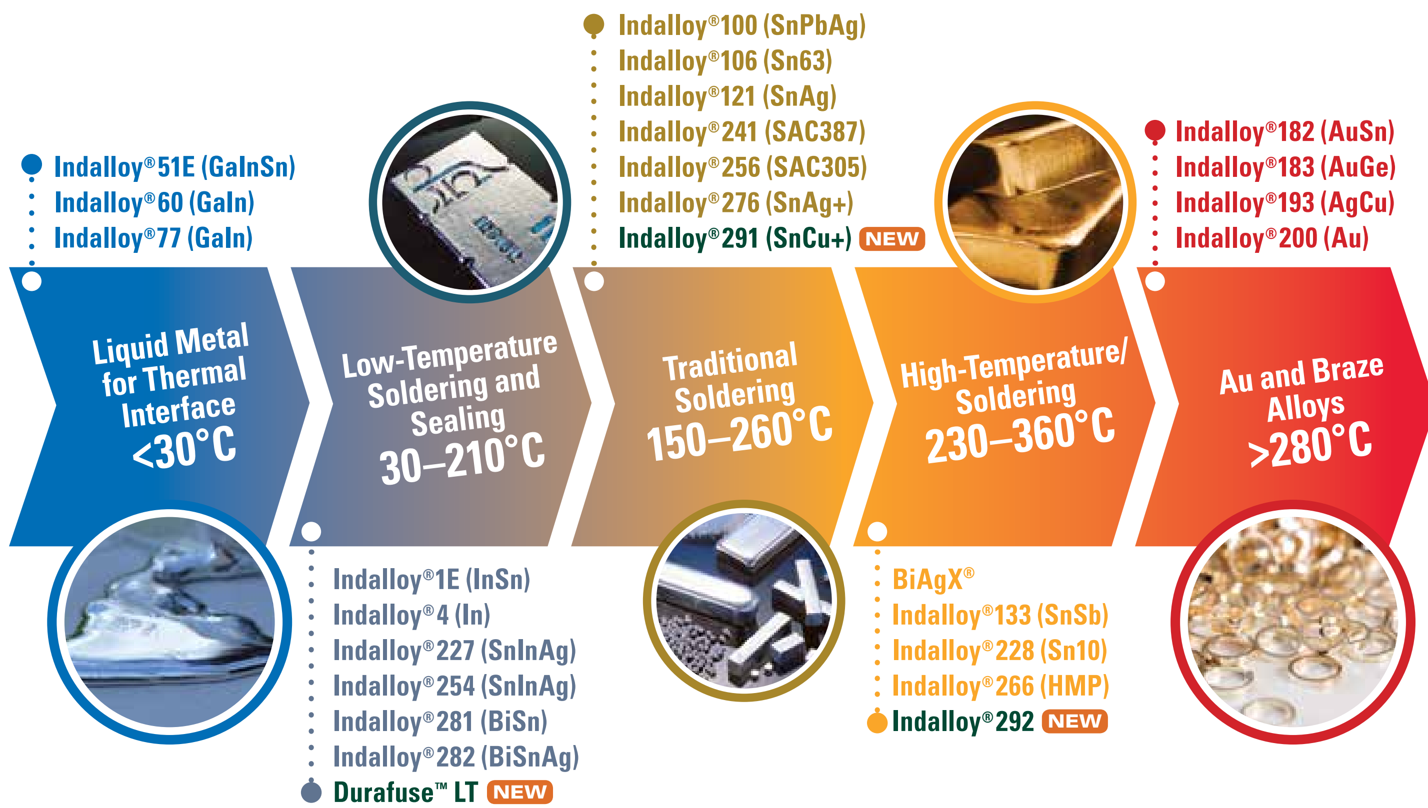
- Over 800 solder alloys available
- Tight tolerance gives precise solder volume
- Standard and custom shapes and thicknesses
- Uniformly flux-coated preforms also available

Indium3.2HF Solder Paste with Indalloy®121

Industry-proven water-soluble solder paste for heat spreader attach

- High thermal conductivity
- Low-voiding
- Long working life
- Easy residue cleaning with DI water

Continuous Alloy Innovation



Learn more: www.indium.com/PowerElectronics
Contact our engineers: askus@indium.com

From One Engineer To Another®

All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.

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Solutions for
Power Electronics

Indium Corporation is the leader in power electronics assembly materials.

Solder Redefined™

Solder and Thermal Solutions for ALL Power Electronics Devices

Substrate-/Spacer-Attach Solutions
- Uniform bondline
- Low-voiding

Die-Attach Solutions
- Uniform bondline
- Dependable standoff heights

Thermal Solutions
- Low thermal resistance
- No pump-out or bake-out

Low Power Density — High Power Density

Recommended products for power electronics

InFORMS®

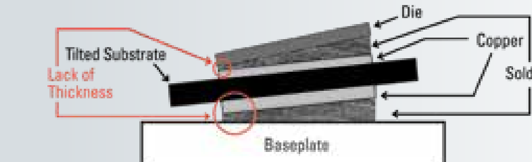
Reinforced Solder Preforms and Ribbon*

Produce consistent bondline thickness on die- and substrate-level

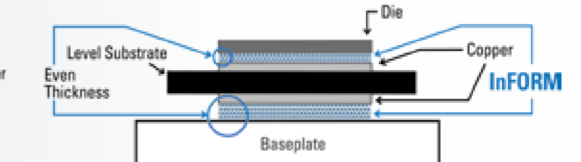
- >2X increase in reliability (-55/+150°C) passes 3,500 thermal cycles
- Most uniform bondline control
- Improved strength and dependable standoff heights

**Patent pending*

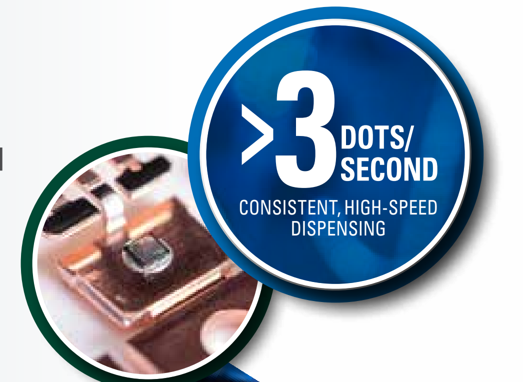
Problem:



Solved:



QuickSinter® NEW



Silver Sintering Paste

Pressureless sintering solution with pressurized sintering capabilities

- Excellent joint strength
- Controllable bondline thickness from 30–70µm
- Versatile sintering profiles

Heat-Spring®

Metal Thermal Interface Materials (Sn+)

Prevent the power die from overheating

- Patterned, compressible interface
- Optimizes performance between the heat source and a heat-sink
- No pump-out or bake-out over time